

Maximum Ratings at $T_A = 25^{\circ}$ C, unless otherwise specified

Parameter	Symbol Value		Unit			
ESD contact/ air discharge ¹⁾	V _{ESD}	20	kV			
Peak pulse current ($t_p = 8 / 20 \ \mu s$) ²⁾	I _{pp}	3	A			
Operating temperature range	T _{op}	-40125	°C			
Storage temperature	T _{stg}	-65150				

Electrical Characteristics at $T_A = 25^{\circ}$ C, unless otherwise specified

Parameter	Symbol	Values			Unit
		min.	typ.	max.]
Characteristics -	·	•			
Reverse working voltage	V _{RWM}	-	-	5.3	V
Breakdown voltage	V _(BR)	6	-	-	
$I_{(BR)}$ = 1 mA, from pin 1 to 3					
Reverse current	I _R	-	< 1	50	nA
V_{R} = 5.3 V, from pin 1 to 3					
Clamping voltage	V _{CL}				V
$I_{\rm PP}$ = 1 A, $t_{\rm p}$ = 8/20µs ²⁾ , from 1/2 to 3		-	10	13	
$I_{\rm PP}$ = 3 A, $t_{\rm p}$ = 8/20µs ²⁾ , from 1/2 to 3		-	12	15	
Forward clamping voltage	V _{FC}				
$I_{\rm PP}$ = 1 A, $t_{\rm p}$ = 8/20µs ²⁾ , from 3 to 1/2		-	2	4	
$I_{\rm PP}$ = 3 A, $t_{\rm p}$ = 8/20µs ²⁾ , from 3 to 1/2		-	4	6	
Line capacitance, $V_R = 0 V$, $f = 1 MHz$	CT				pF
from pin 1/2 to $3^{3)}$		-	0.4	0.6	
from pin 1 to 2, pin 3 not connected		-	0.2	0.4	

 $^{1}V_{\text{ESD}}$ according to IEC61000-4-2

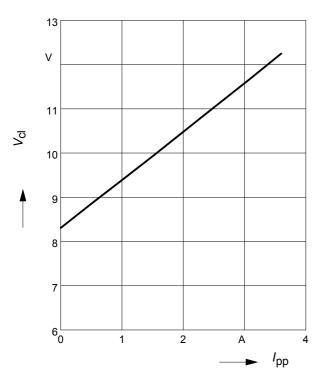
 $^2\textit{I}_{pp}$ according to IEC61000-4-5

³Total capacitance line to ground

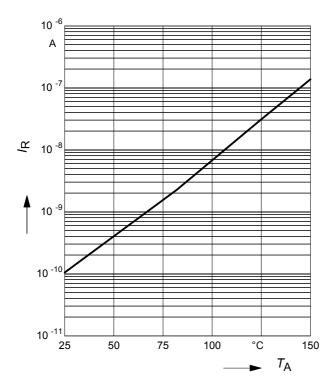


Clamping voltage, $V_{cl} = f(I_{pp})$

 $t_{\rm p}$ = 8 / 20 µs, from pin 1/2 to 3

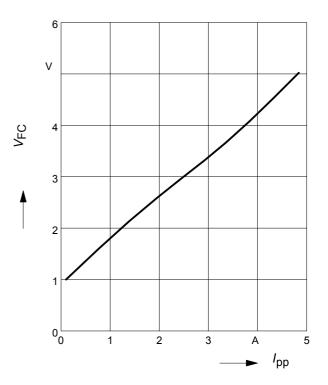


Reverse current $I_{R} = f(T_{A})$ V_{R} = Parameter, from pin 1/2 to 3

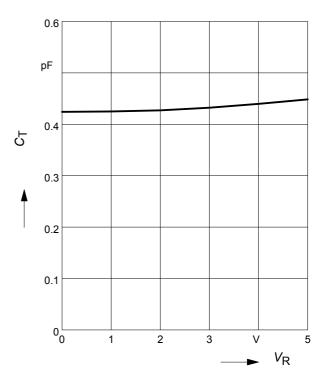


Forward clamping voltage $V_{FC} = f(I_{PP})$

 $t_{\rm p}$ = 8 / 20 µs, from pin 3 to 1/2



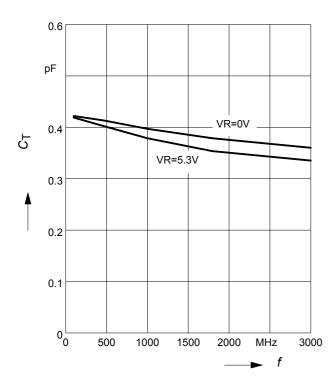
Diode capacitance $C_{T} = f(V_{R})$ f = 1MHz, from pin 1/2 to 3





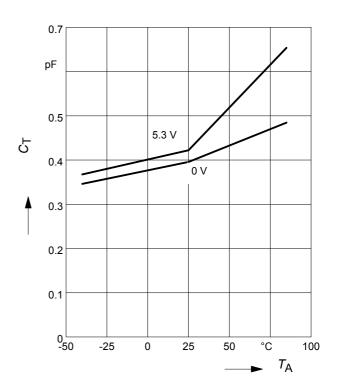
Line capacitance $C_T = f$ (f)

 V_{R} = parameter, from pin 1/2 to 3



Line capacitance $C_{T} = f(T_{A})$

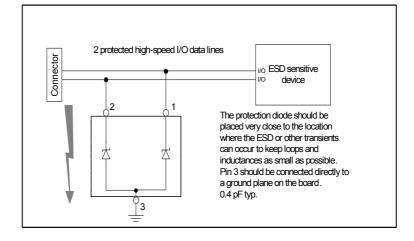
 $V_{\rm R} = 0 \, {\rm V}, \, f = 1 \, {\rm MHz}$





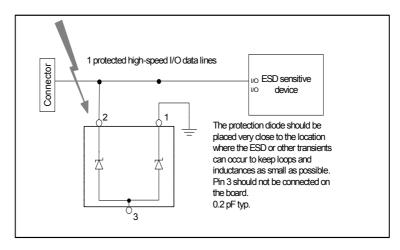
Application example ESD5V3U2U...

2 lines, uni-directional

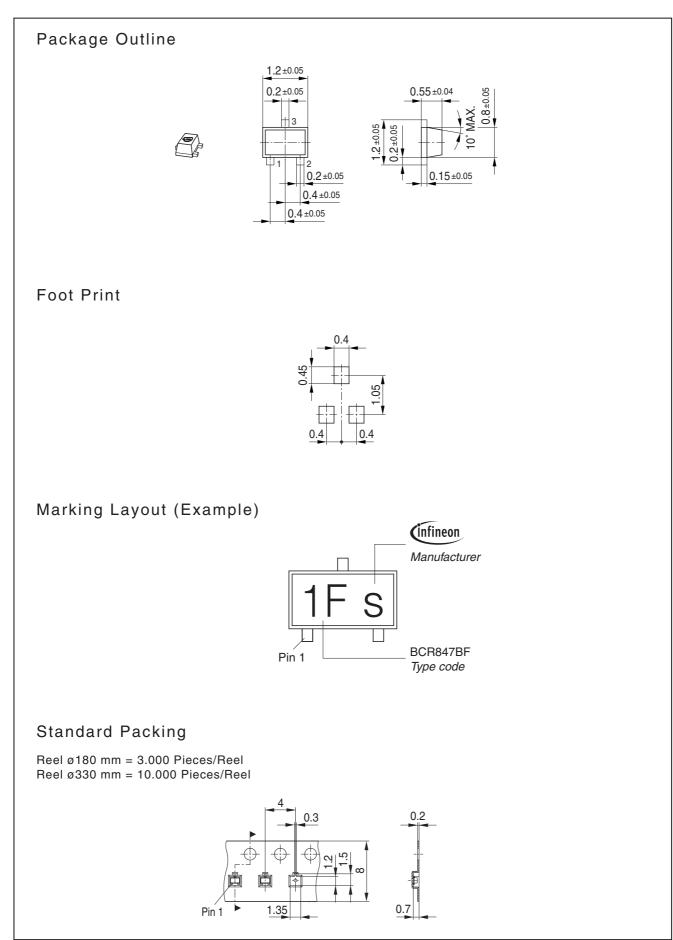


Application example ESD5V3U2U...

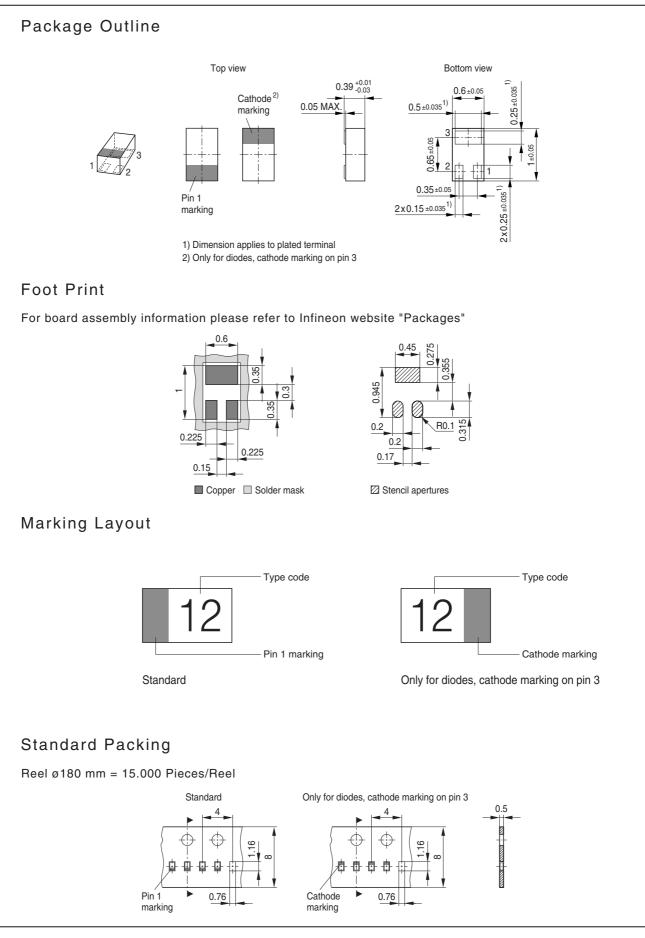
1 line, bi-directional















Edition 2009-11-16

Published by Infineon Technologies AG 81726 Munich, Germany

© 2009 Infineon Technologies AG All Rights Reserved.

Legal Disclaimer

The information given in this document shall in no event be regarded as a guarantee of conditions or characteristics. With respect to any examples or hints given herein, any typical values stated herein and/or any information regarding the application of the device, Infineon Technologies hereby disclaims any and all warranties and liabilities of any kind, including without limitation, warranties of non-infringement of intellectual property rights of any third party.

Information

For further information on technology, delivery terms and conditions and prices, please contact the nearest Infineon Technologies Office (<<u>www.infineon.com</u>>).

Warnings

Due to technical requirements, components may contain dangerous substances. For information on the types in question, please contact the nearest Infineon Technologies Office.

Infineon Technologies components may be used in life-support devices or systems only with the express written approval of Infineon Technologies, if a failure of such components can reasonably be expected to cause the failure of that life-support device or system or to affect the safety or effectiveness of that device or system. Life support devices or systems are intended to be implanted in the human body or to support and/or maintain and sustain and/or protect human life. If they fail, it is reasonable to assume that the health of the user or other persons may be endangered.